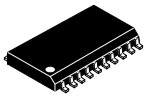
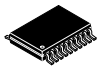
Low-Voltage Octal Buffer/Line Driver with 5 V Tolerant Inputs and Outputs

74LCX541



SOIC-20 WB
DW SUFFIX
CASE 751D



TSSOP-20
DT SUFFIX
CASE 948E

The LCX541 is an octal buffer/line driver designed to be employed as memory and address drivers, clock drivers and bus oriented transmitter/receivers. The LCX541 is a non-inverting option of the LCX540.

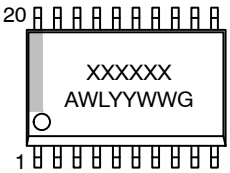
This device is similar in function to the LCX244 while providing flow-through architecture (inputs on opposite side from outputs). This pinout arrangement makes this device especially useful as an output port for microprocessors, allowing ease of layout and greater PC board density.

The LCX541 is designed for low voltage applications with capability of interfacing to a 5 V signal environment. The LCX541 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

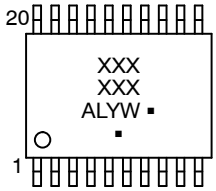
Features

- 5 V Tolerant Input and Outputs
- 1.65 V–5.5 V V_{CC} Specifications Provided
- 6.5 ns t_{PD} Max. (V_{CC} = 3.3 V), 10 μA ICC Max.
- Power-down High Impedance Inputs and Outputs
- Supports Live Insertion/Withdrawal
- ±24 mA Output Drive (V_{CC} = 3.0 V)
- Implements Proprietary Noise/ EMI Reduction Circuitry
- Latch-up Performance Exceeds JEDEC 78 Conditions
- ESD Performance
  - ♦ Human Body Model > 2000 V
- Pb-Free DQFN Package
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MARKING DIAGRAM



SOIC-20 WB



TSSOP-20

A	=	Assembly Location
L, WL	=	Wafer Lot
Y, YY	=	Year
W, WW	=	Work Week
G or ▪	=	Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

Connection Diagrams

Pin Assignments for SOIC, SOP, SSOP, TSSOP

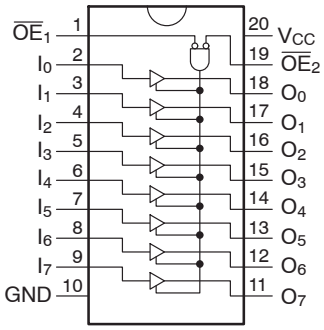


Figure 1.

Logic Symbol

IEEE/IEC

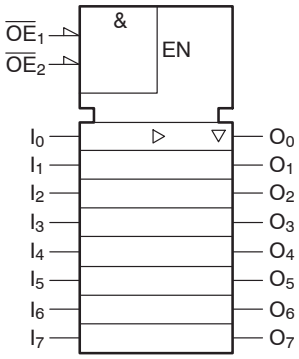
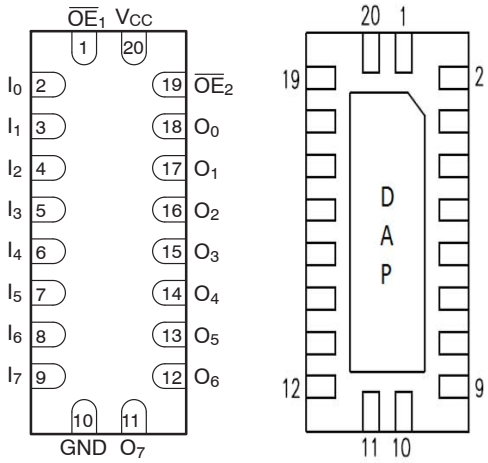


Figure 2.

Pad Assignment for DQFN



(Top View) **(Bottom View)**

Figure 3.

PIN DESCRIPTION

Pin	Description
$\overline{OE}_1$, $\overline{OE}_2$	3-STATE Output Enable Inputs
I_0–I_7	Inputs
O_0–O_7	Outputs
DAP	No Connect

TRUTH TABLE

Inputs			Outputs
$\overline{OE}_1$	$\overline{OE}_2$	I_n	O_n
L	L	H	H
L	X	X	Z
X	H	X	Z
L	L	L	L

H = High Voltage Level
L = Low Voltage Level
X = Immaterial
Z = High Impedance State

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +6.5	V
V_I	DC Input Voltage (Note 1)		−0.5 to +6.5	V
V_O	DC Output Voltage (Note 1)	Active-Mode (High or Low State) Tri-State Mode Power-Down Mode (V_{CC} = 0 V)	−0.5 to V_{CC}+0.5 −0.5 to +6.5 −0.5 to +6.5	V
I_{IK}	DC Input Diode Current	V_{IN} < GND	−50	mA
I_{OK}	DC Output Diode Current	V_{OUT} < GND	−50	mA
I_O	DC Output Source/Sink Current		±50	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin		±100	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 secs		260	°C
T_J	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SOIC-20W WQFN20 TSSOP-20	96 99 150	°C/W
P_D	Power Dissipation in Still Air	SOIC-20W WQFN20 TSSOP-20	1302 1256 833	mW
MSL	Moisture Sensitivity	SOIC-20W All Other Packages	Level 3 Level 1	–
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	–
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.
2. Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
3. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A.

RECOMMENDED OPERATING CONDITIONS (Note 4)

Symbol	Parameter		Min	Max	Unit
V_{CC}	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
V_I	Digital Input Voltage		0	5.5	V
V_O	Output Voltage	Active Mode (High or Low State) Tri-State Mode Power Down Mode (V_{CC} = 0 V)	0 0 0	V_{CC} 5.5 5.5	V
T_A	Operating Free-Air Temperature		−40	+125	°C
t_r, t_f	Input Rise or Fall Rate	V_{CC} = 1.65 V to 1.95 V V_{CC} = 2.3 V to 2.7 V V_{IN} from 0.8 V to 2.0 V, V_{CC} = 3.0 V V_{CC} = 4.5 V to 5.5 V	0 0 0 0	20 20 10 5	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V_{CC} (V)	T_A = −40°C to +85°C		T_A = −40°C to +125°C		Unit
				Min	Max	Min	Max	
V_{IH}	High-Level Input Voltage		1.65 to 1.95	0.65 x V_{CC}		0.65 x V_{CC}		V
			2.3 to 2.7	1.7		1.7		
			2.7 to 3.6	2.0		2.0		
			4.5 to 5.5	0.7 x V_{CC}		0.7 x V_{CC}		
V_{IL}	Low-Level Input Voltage		1.65 to 1.95		0.35 x V_{CC}		0.35 x V_{CC}	V
			2.3 to 2.7		0.7		0.7	
			2.7 to 3.6		0.8		0.8	
			4.5 to 5.5		0.3 x V_{CC}		0.3 x V_{CC}	
V_{OH}	High-Level Output Voltage	V_I = V_{IH} or V_{IL}						V
		I_{OH} = −100 μA	1.65 to 5.5	V_{CC} − 0.1	–	V_{CC} − 0.1	–	
		I_{OH} = −4 mA	1.65	1.2	–	1.2	–	
		I_{OH} = −8 mA	2.3	1.8	–	1.8	–	
		I_{OH} = −12 mA	2.7	2.2	–	2.2	–	
		I_{OH} = −16 mA	3.0	2.4	–	2.4	–	
		I_{OH} = −24 mA	3.0	2.2	–	2.2	–	
		I_{OH} = −32 mA	4.5	3.8		3.8		
V_{OL}	Low-Level Output Voltage	V_I = V_{IH} or V_{IL}						V
		I_{OL} = 100 μA	1.65 to 5.5	–	0.1	–	0.1	
		I_{OL} = 4 mA	1.65	–	0.45	–	0.45	
		I_{OL} = 8 mA	2.3	–	0.6	–	0.6	
		I_{OL} = 12 mA	2.7	–	0.4	–	0.4	
		I_{OL} = 16 mA	3.0	–	0.4	–	0.4	
		I_{OL} = 24 mA	3.0	–	0.55	–	0.55	
		I_{OL} = 32 mA	4.5		0.6		0.6	
I_I	Input Leakage Current	V_I = 0 to 5.5 V	3.6	–	±5.0	–	±5.0	μA
I_{OZ}	3-State Output Leakage Current	V_I = V_{IH} or V_{IL}, V_O = 0 V to 5.5 V	3.6	–	±5.0	–	±5.0	μA
I_{OFF}	Power Off Leakage Current	V_I = 5.5 V or V_O = 5.5 V	0	–	10	–	10	μA
I_{CC}	Quiescent Supply Current	V_I = 5.5 V or GND	2.3 to 3.6	–	10	–	10	μA
		3.6 V ≤ V_I, V_O ≤ 5.5 V (Note 5)			±10.0		±10.0	
ΔI_{CC}	Increase in I_{CC} per Input	V_{IH} = V_{CC} − 0.6 V	2.3 to 3.6	–	500	–	500	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Outputs disabled or 3-STATE only.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Condition	V_{CC} (V)	T_A = −40°C to +85°C		T_A = −40°C to +125°C		Unit
				Min	Max	Min	Max	
t_{PLH}, t_{PHL}	Propagation Delay, D to O	See Figures 4 and 5	1.65 to 1.95	–	10.3	–	10.3	ns
			2.3 to 2.7	–	7.8	–	7.8	
			2.7	–	7.5	–	7.5	
			3.0 to 3.6	–	6.5	–	6.5	
			4.5 to 5.5	–	5.9	–	5.9	
t_{PZH}, t_{PZL}	Output Enable Time, $\overline{OE}$ to O	See Figures 4 and 5	1.65 to 1.95	–	13.0	–	13.0	ns
			2.3 to 2.7	–	10.5	–	10.5	
			2.7	–	9.5	–	9.5	
			3.0 to 3.6	–	8.5	–	8.5	
			4.5 to 5.5	–	7.3	–	7.3	
t_{PHZ}, t_{PLZ}	Output Disable Time, $\overline{OE}$ to O	See Figures 4 and 5	1.65 to 1.95	–	11.0	–	11.0	ns
			2.3 to 2.7	–	9.0	–	9.0	
			2.7	–	8.5	–	8.5	
			3.0 to 3.6	–	7.5	–	7.5	
			4.5 to 5.5	–	6.5	–	6.5	
t_{OSHL}, t_{OSLH}	Output to Output Skew (Note 6)		1.65 to 1.95	–	–	–	–	ns
			2.3 to 2.7	–	–	–	–	
			2.7	–	–	–	–	
			3.0 to 3.6	–	1.0	–	1.0	

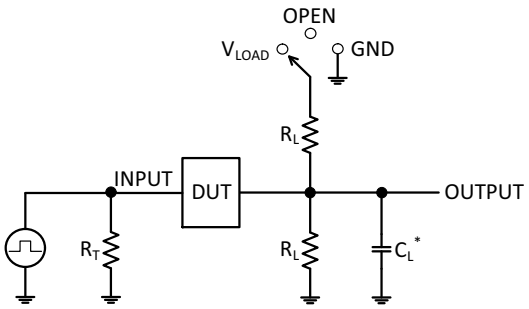
6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \times V_{CC} \times f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption: $P_D = C_{PD} \times V_{CC}^2 \times f_{in} + I_{CC} \times V_{CC}$.

DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = 25°C	Unit
				Typ	
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	3.3	C_L = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V	0.8	V
		2.5	C_L = 30 pF, V_{IH} = 2.5 V, V_{IL} = 0 V	0.6	
V_{OLV}	Quiet Output Dynamic Valley V_{OL}	3.3	C_L = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V	−0.8	V
		2.5	C_L = 30 pF, V_{IH} = 2.5 V, V_{IL} = 0 V	−0.6	

CAPACITANCE

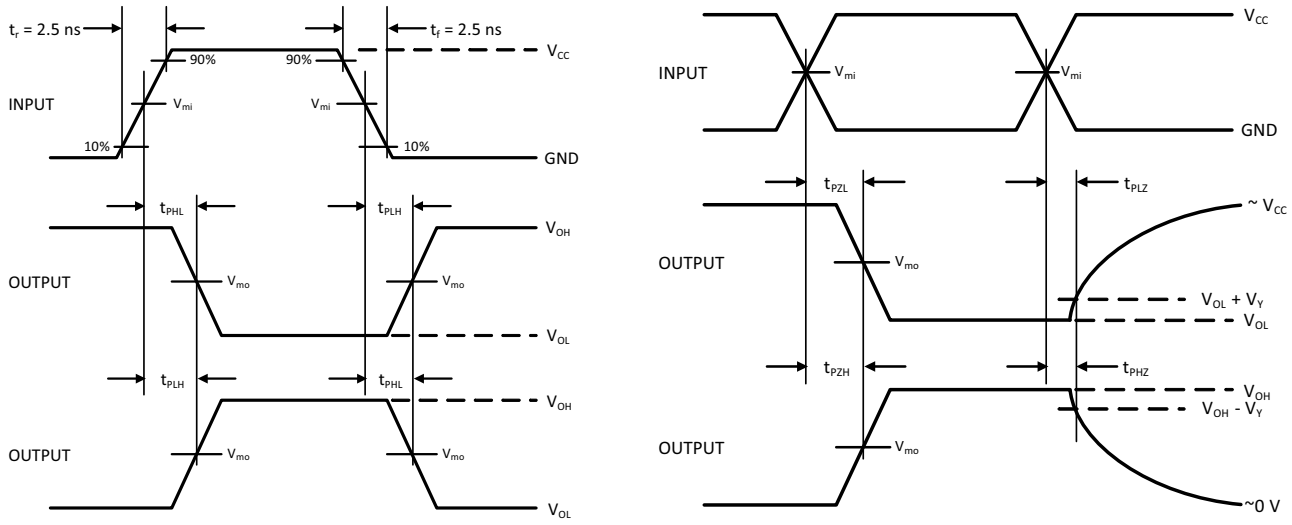
Symbol	Parameter	Conditions	Typ	Unit
C_{IN}	Input Capacitance	V_{CC} = Open, V_I = 0 V or V_{CC}	7.0	pF
C_{OUT}	Output Capacitance	V_{CC} = 3.3 V, V_I = 0 V or V_{CC}	8.0	pF
C_{PD}	Power Dissipation Capacitance	V_{CC} = 3.3 V, V_I = 0 V or V_{CC}, f = 10 MHz	25.0	pF



Test	Switch Position
t_{PLH} / t_{PHL}	Open
t_{PLZ} / t_{PZL}	V_{LOAD}
t_{PHZ} / t_{PZH}	GND

*C_L includes probe and jig capacitance
R_T is Z_{OUT} of pulse generator (typically 50 Ω)
f = 1 MHz

Figure 4. Test Circuit



V_{CC}, V	R_L, Ω	C_L, pF	V_{LOAD}	V_{mi}, V	V_{mo}, V	V_Y, V
1.65 to 1.95	500	30	2 x V_{CC}	V_{CC}/2	V_{CC}/2	0.15
2.3 to 2.7	500	30	2 x V_{CC}	V_{CC}/2	V_{CC}/2	0.15
2.7	500	50	6 V	1.5	V_{CC}/2	0.3
3.0 to 3.6	500	50	6 V	1.5	V_{CC}/2	0.3
4.5 to 4.5	500	50	2 x V_{CC}	V_{CC}/2	V_{CC}/2	0.3

Figure 5. Switching Waveforms

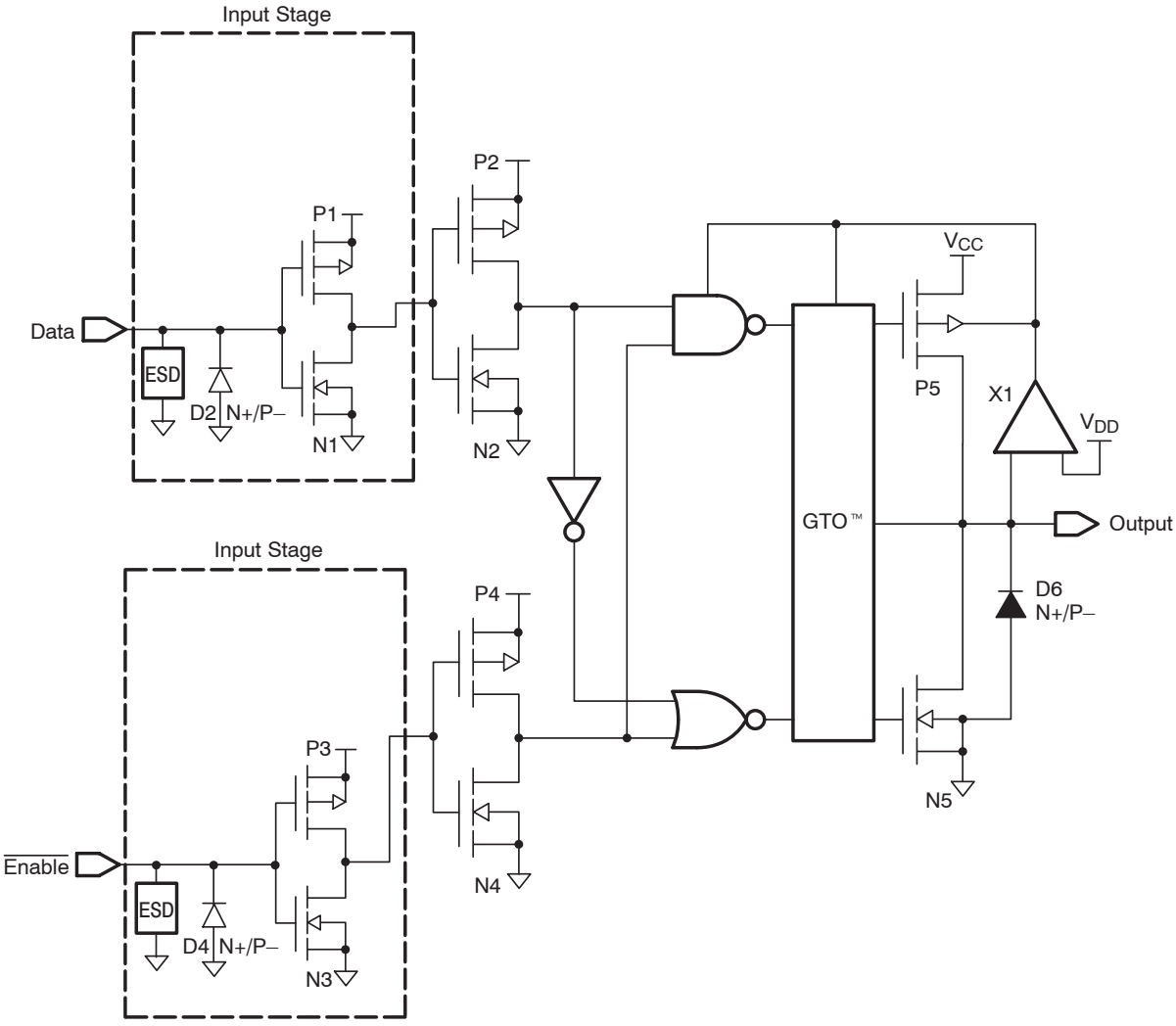


Figure 6. Schematic Diagram
(Generic for LCX Family)

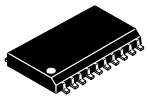
ORDERING INFORMATION

Device	Marking	Package	Shipping†
74LCX541WMX	LCX541	SOIC-20 WB	1000 / Tape & Reel
74LCX541MTC	LCX 541	TSSOP-20	75 Units / Tube
74LCX541MTCX	LCX 541	TSSOP-20	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SOIC−20 WB
CASE 751D−05
ISSUE H

DATE 22 APR 2015



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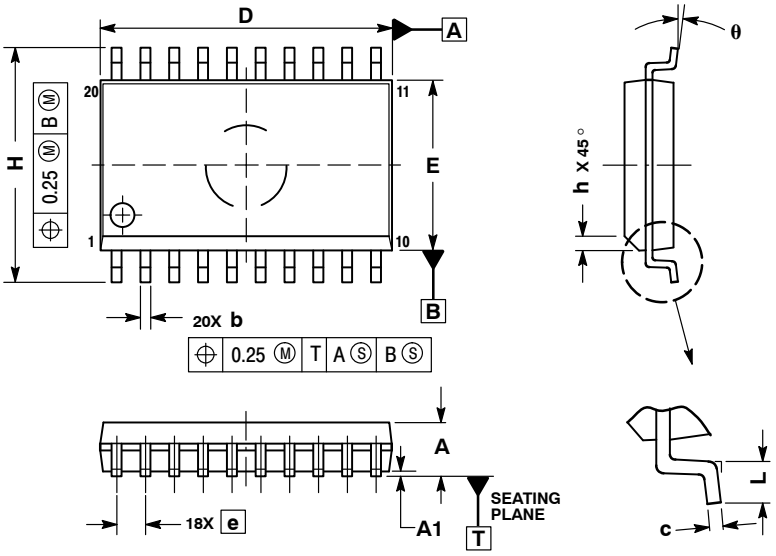
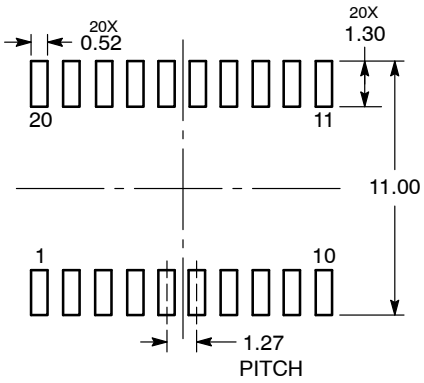


NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

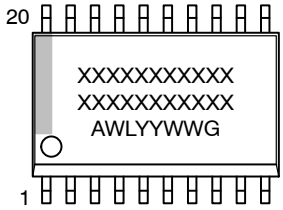
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



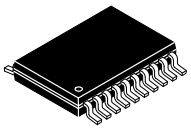
XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98ASB42343B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
DESCRIPTION:	**SOIC−20 WB**		**PAGE 1 OF 1**

TSSOP–20 WB
CASE 948E
ISSUE D

DATE 17 FEB 2016



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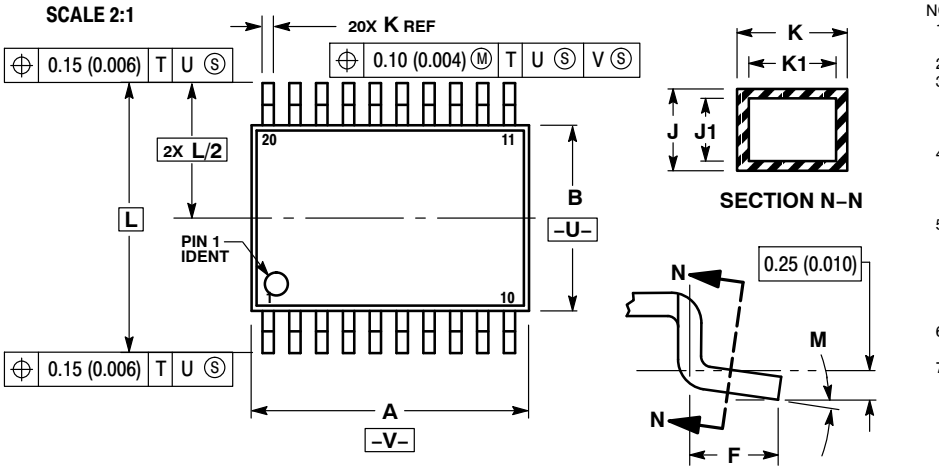
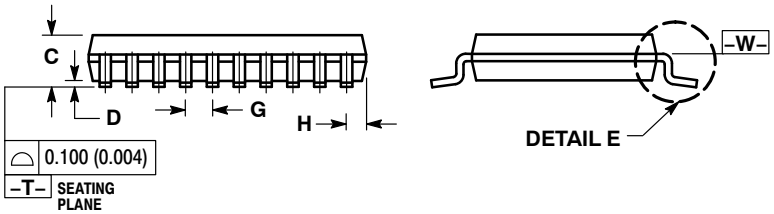


SECTION N–N

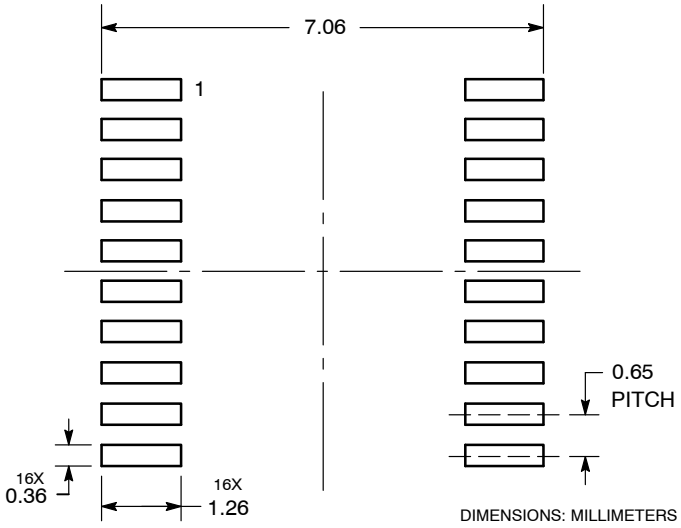
DETAIL E



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

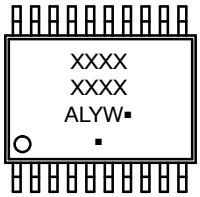
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb–Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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